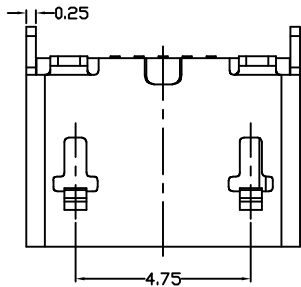
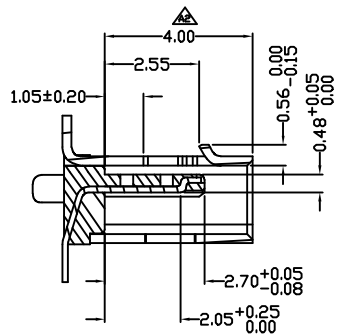


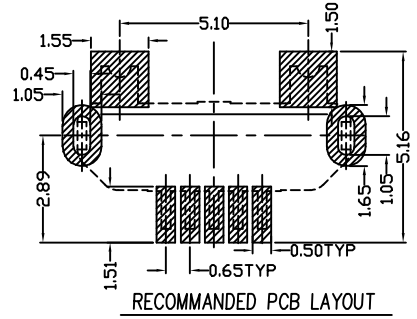
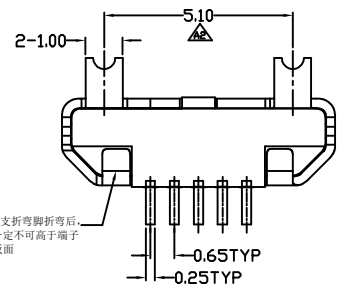
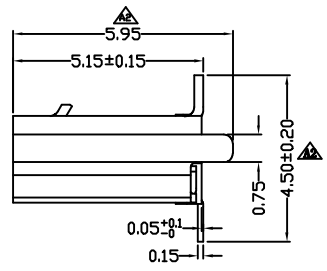
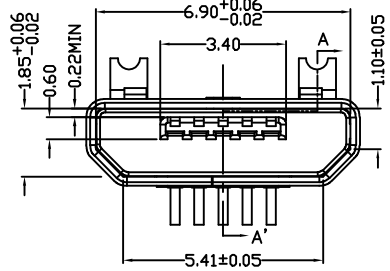
REV.	ECN.NO.	APPD.
AO	/	/



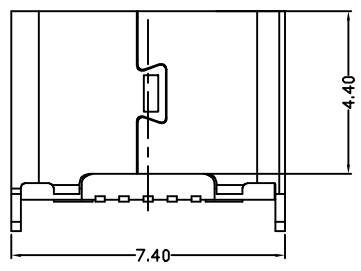
- Note:
- Material:
 - Housing: High temperature thermoplastic with g.f, UL94v-0
 - Contact: copper alloy, t=0.20mm
 - Shell: copper alloy, t=0.25mm
 - Specification:
 - Current rating: 1 A Max
 - Dielectric withstanding voltage: 100V(ac) for 1 Min
 - Contact resistance: 50MW Max
 - Insulation resistance: 100MW Min
 - Total mating force: 3.57kgf Max
 - Total unmating force: 1.0kgf Min. 0.81~2.05 kgf Min
 - Temperature range: -30°C~80°C



SECTION A-A'



RECOMMENDED PCB LAYOUT



U443-214X-XXX0X8

- 1:Iron alloy Ni plating
- 5:Copper alloy Ni plating
- A:stainless steel tin plating
- B:stainless steel Ni plating
- 1:Au 1u"
- 8:Au 15u"
- A:Au 30u"
- 1:tray
- 2:Tube
- 3:Tape&Reel
- 9:Tape&Reel+Mylar
- 1:Black
- 2:Cool grey
- 5:PA9T
- 2:PBT
- 6:LCP

TOLERANCE UNLESS OTHERWISE SPECIFIED		FLW 深圳市华联威电子科技有限公司			
		HUA LIAN WEI TECHNOLOGY ELECTRONICS CO;LTD.			
.XXX ±0.10 .XX ±0.20 .X ±0.30		.X' ±3' .XX' ±2'		PART NAME: MICRO 5/F 180度立式贴片卷带H款	
APPROVED		PART No:	U443-214X-XXX018		C
CHECKED		PROJECTION:	UNIT:	SCALE:	SHEET:
DRAWN			mm	1:1	10F1
DATE					REV. AO